



2-28-03

2815

Express Mail No.: EL 451 599 709 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Mohammad Eslamy

Application No.: 09/938,075

Group Art Unit: 2815

Filed: August 23, 2001

Examiner: Joseph H. Nguyen

For: SYMMETRIC STACK UP
STRUCTURE FOR ORGANIC
BGA CHIP CARRIERS

Attorney Docket No.: 9818-055-999

#8/B
3/5/3
Surles

RESPONSE TO THE OFFICE ACTION DATED NOVEMBER 29, 2002

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated November 29, 2002, entry of the following amendments and remarks is respectfully requested.

TECHNOLOGY CENTER 2800
MAR -4 2003
RECEIVED

AMENDMENT

IN THE CLAIMS:

A marked up version of the revised claims, showing insertions and deletions is included in the Appendix attached hereto.

Please rewrite the pending claims as follows:

- B'
9. (Twice Amended) A semiconductor chip carrier comprising:
a primary substrate;
a metal heat sink plate, whose thermal coefficient of expansion is substantially different from that of said primary substrate, having a first side and an opposing second side where said primary substrate is attached to said first side;
a supplemental substrate being attached to said second side of said metal heat sink plate, wherein said metal heat sink plate is between said primary substrate and said supplemental substrate; and